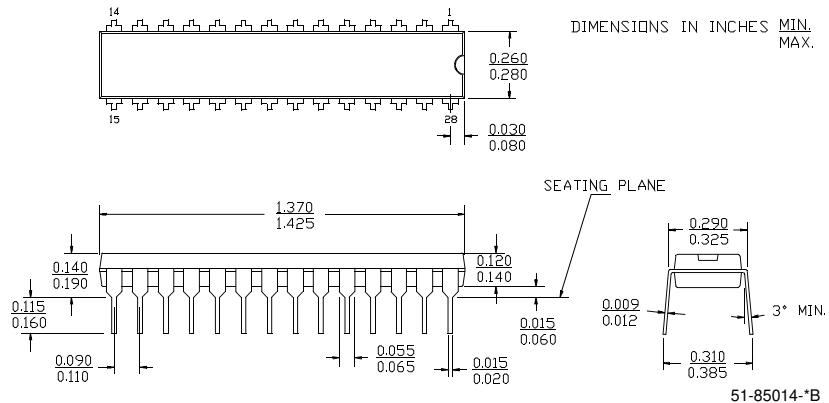
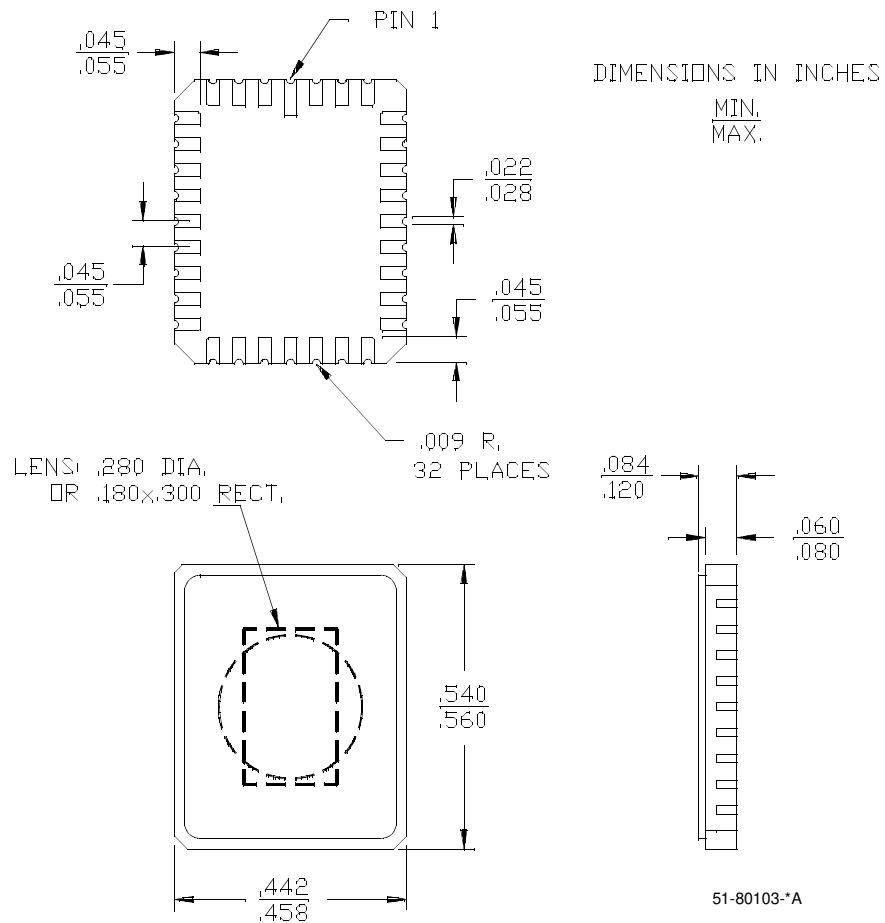
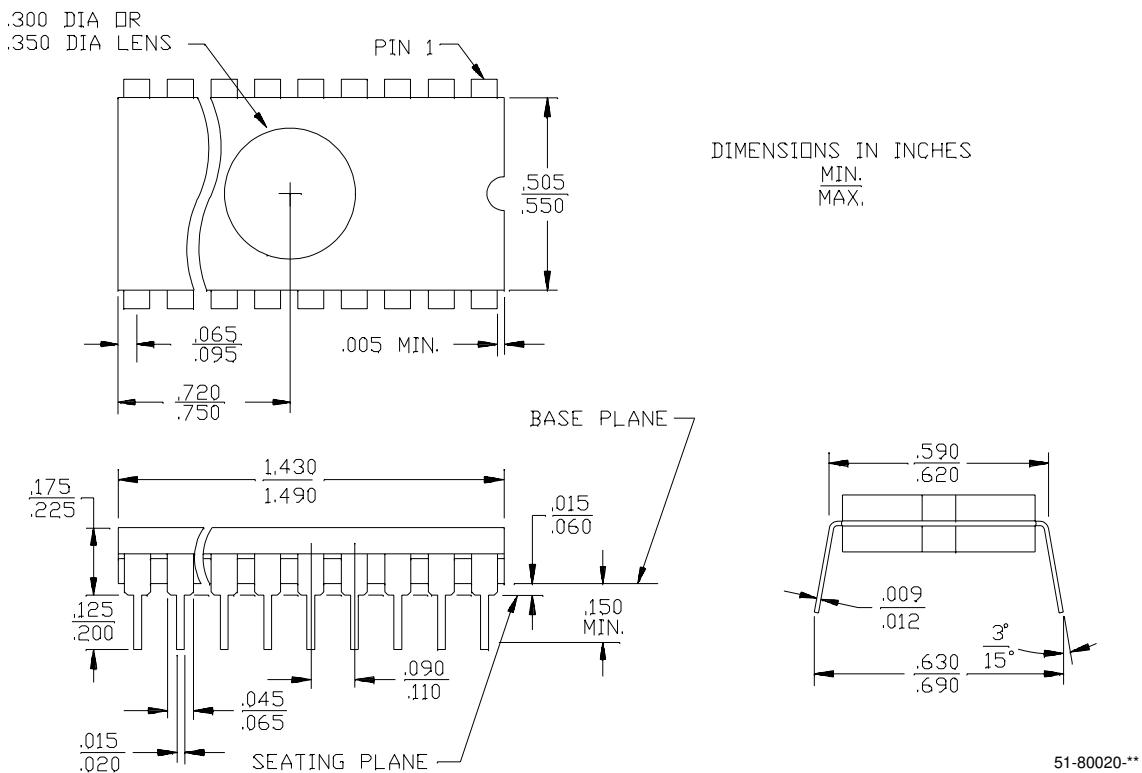
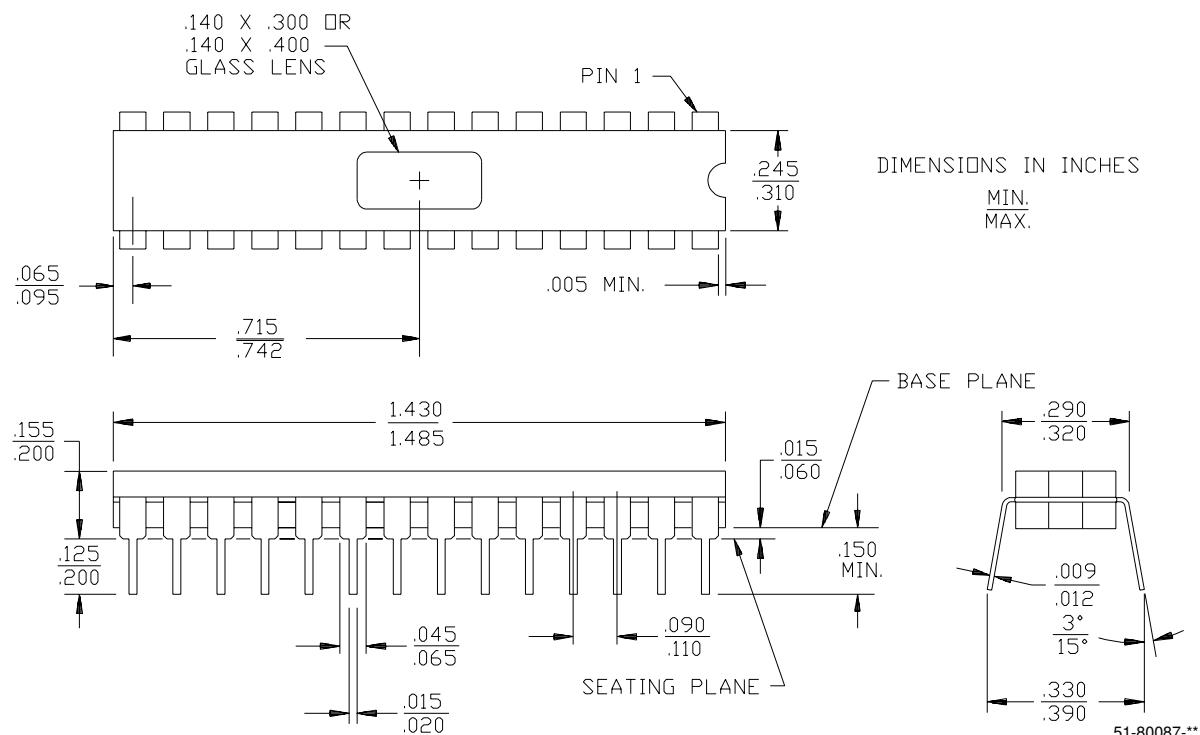


Package Diagrams
28-Lead (300-Mil) Molded DIP P21

**32-Pin Windowed Rectangular Leadless Chip Carrier Q55
MIL-STD-1835 C-12**


Package Diagrams (continued)

28-Lead (600-Mil) Windowed CerDIP W16
 MIL-STD-1835 D-10 Config. A



Package Diagrams (continued)
28-Lead (300-Mil) Windowed CerDIP W22
MIL-STD-1835 D-15 Config. A


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CY7C271
CY7C274

Document History Page

Document Title: CY7C271 CY7C274 32K x 8 Power Switched and Reprogrammable PROM
Document Number: 38-04008

| REV. | ECN NO. | Issue Date | Orig. of Change | Description of Change |
|------|---------|------------|-----------------|---|
| ** | 113864 | 3/8/02 | DSG | Change from Spec number: 38-00068 to 38-04008 |
| A* | 118899 | 10/10/02 | GBI | Updating Ordering Information |
| *B | 122249 | 12/27/02 | RBI | Add power up requirements to Operating Conditions information |